

EDGE HANDLING WAFER PREALIGNER

LPA12ET-3

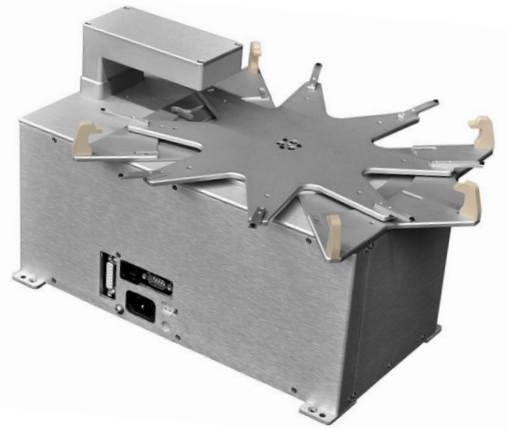
Innovative, high-performance, all-in-one design eliminates external controller and interconnecting cables while maintaining drop-in compatibility

Driven by ultra low inertia brushless motors for **smooth, instant response**

Advanced scanning electronics capable of detecting **transparent, semi-transparent and opaque objects** without mechanical repositioning between different wafer sizes

Motion control software featuring a comprehensive set of commonly used commands enabling **compatibility and interface with a variety of semiconductor platforms**

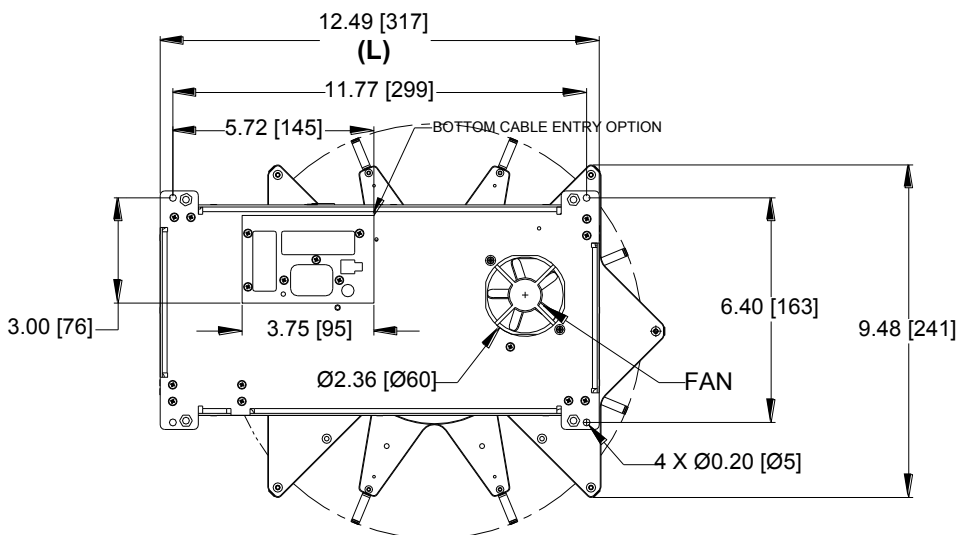
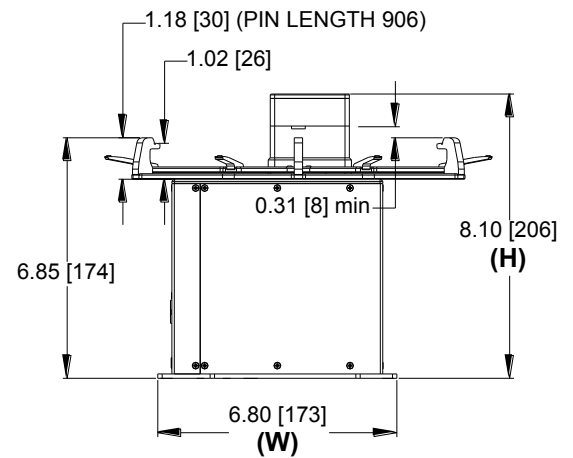
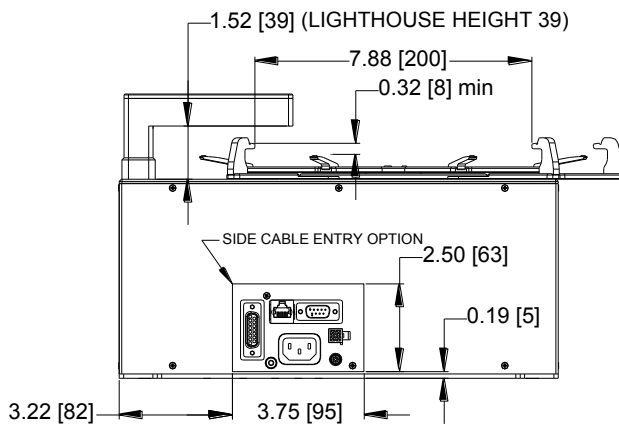
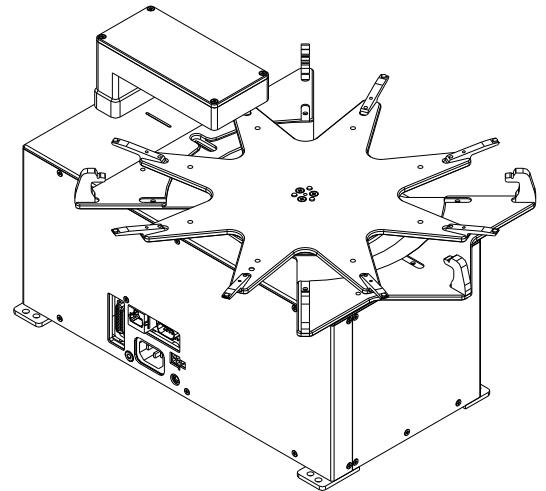
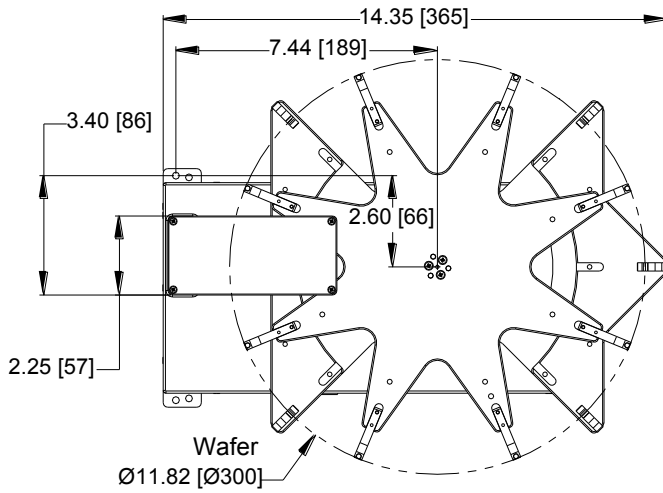
Typical alignment cycle time of less than four seconds facilitates the achievement of **maximum system throughput**



LPA12ET-3 SPECIFICATIONS

Wafer Diameter		300mm
Wafer Opacity		Transparent, Semi-Transparent, Opaque
Square Substrates		Not Applicable
Wafer Handling		Edge Handling
Centering Accuracy		±25um on the Prealigner Chuck
Angular Accuracy (3 Sigma)	10000 CPR Encoder	±0.04° on the Prealigner Chuck
	24000 CPR Encoder	±0.02° on the Prealigner Chuck
Servo Axes		Three
Host Communication		RS232, Ethernet
Max Initial Wafer Offset		1.7mm
Body Dimensions (W x L x H)		173mm x 317mm x 206mm
Footprint Compatibility		LPA8ET-3 LPA312-3, LPA812-3, LPA1218-3
Weight		6.00kg
Facilities Required		100-240VAC, 50/60Hz, 48VA, or 24VDC/2A
Flat/Notch Compatibility		SEMI Standards Compliant
Cleanliness		Class 1
MTBF		More than 70000 hours

LPA12ET-3 GENERAL DIMENSIONS



NOTE: All Dimensions — inch [mm]

For model numbers and options download: [LPA Series Prealigners Ordering Guide.pdf](#)